

REMARKS

Applicant cancels claims 1-3, 7-10, 13-15, 21, 22 and 24 without prejudice or disclaimer, and adds new claims 28 and 29. Therefore, claims 4-6, 11, 12, 16, 17, 23 and 25-29 are now pending in the application.

Applicant rewrites allowable claims 11, 16, 26 and 27 in independent form including the limitations of their respective base and intervening claims, without changing the scope of claims 11, 16, 26 and 27. No estoppel is created.

Therefore, claims 4-6, 11, 12, 16, 17, 26 and 27 are now allowed.

Applicant amends claim 23 more clearly to recite the features of the embodiment defined therein, and adds new claims 28 and 29 more fully to cover in the claims various aspects of the invention as described in the specification.

With regard to claims 23 and 25, Applicant respectfully traverses the Examiner's prior art rejection as follows.

Referring to Figs. 16A to 18, Seki (U.S. Patent 6,165,819) shows a bottom surface 16A of external terminal 16 of leads 14. The bottom surface has dimples 16-1 and grooves 16-2. However, bottom surface 16A is connected to electrode pads 52 of the circuit substrate shown in Fig. 14B on which semiconductor device 50 is mounted. That is, such dimples and grooves are provided to electrically positively adhere to the external terminal 16 with the lead.

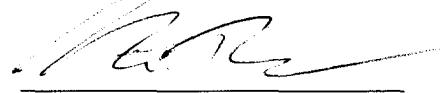
On the other hand, Williams et al. shows in Fig. 19O, lead 470, plate 460 and chip 462. Therefore, if Williams et al. and Seki were combined, the dimples or grooves of Seki would be provided on the bottom surface of lead 470 or the first main surface of plate 460 to which chip 462 is adhered so as to electrically positively connect to each other.

In contrast, Applicant's claim 23 recites a second main surface of the metal plate, which does not connect to any electrodes and has a roughened surface which enhances adhesion strength between the metal plate and the molding resin. Accordingly, Applicant's claim 23, as well as its dependent claims 25 (which incorporates all the novel and unobvious features of its base claim), would not have been obvious to a person having an ordinary skill in the art from the combination of Williams et al. and Seki at least for this reason.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned attorney at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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